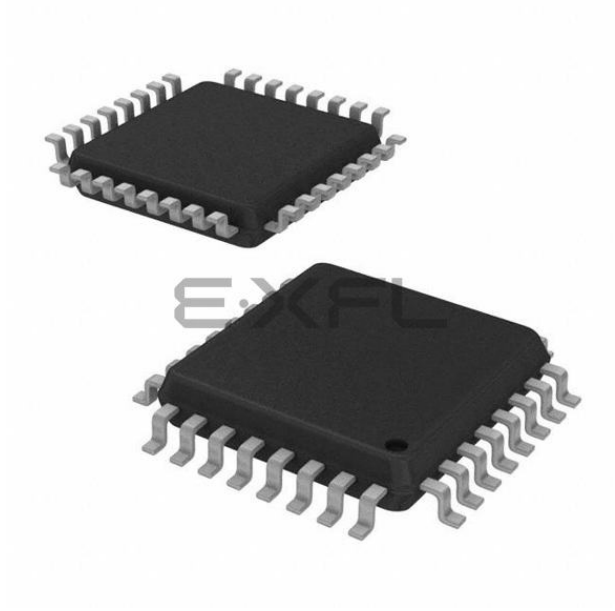

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SMBus (2-Wire/I²C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	24
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	0.9V ~ 3.6V
Data Converters	A/D 23x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f920-gqr

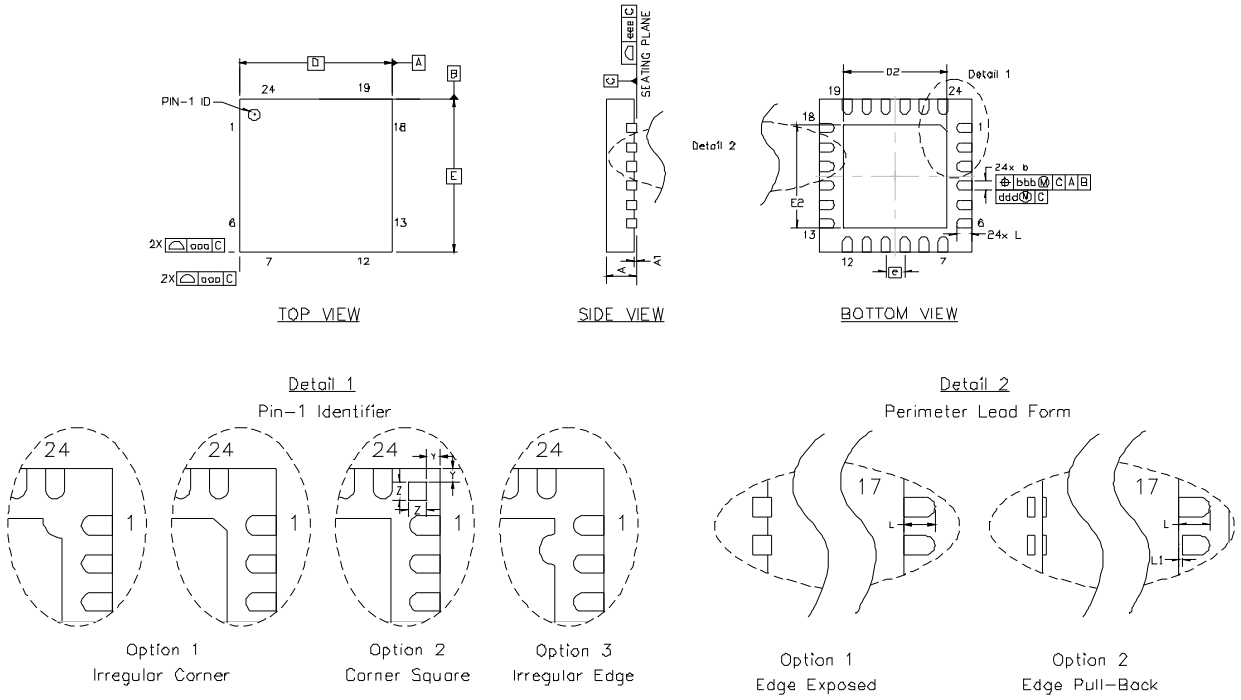


Figure 3.6. QFN-24 Package Drawing

Table 3.4. QFN-24 Package Dimensions

Dimension	Min	Typ	Max
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.18	0.25	0.30
D	4.00 BSC		
D2	2.55	2.70	2.80
e	0.50 BSC		
E	4.00 BSC		
E2	2.55	2.70	2.80

Dimension	Min	Typ	Max
L	0.30	0.40	0.50
L1	0.00	—	0.15
aaa	—	—	0.15
bbb	—	—	0.10
ddd	—	—	0.05
eee	—	—	0.08
Z	—	0.24	—
Y	—	0.18	—

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to the JEDEC Solid State Outline MO-220, variation WGGD except for custom features D2, E2, Z, Y, and L which are toleranced per supplier designation.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

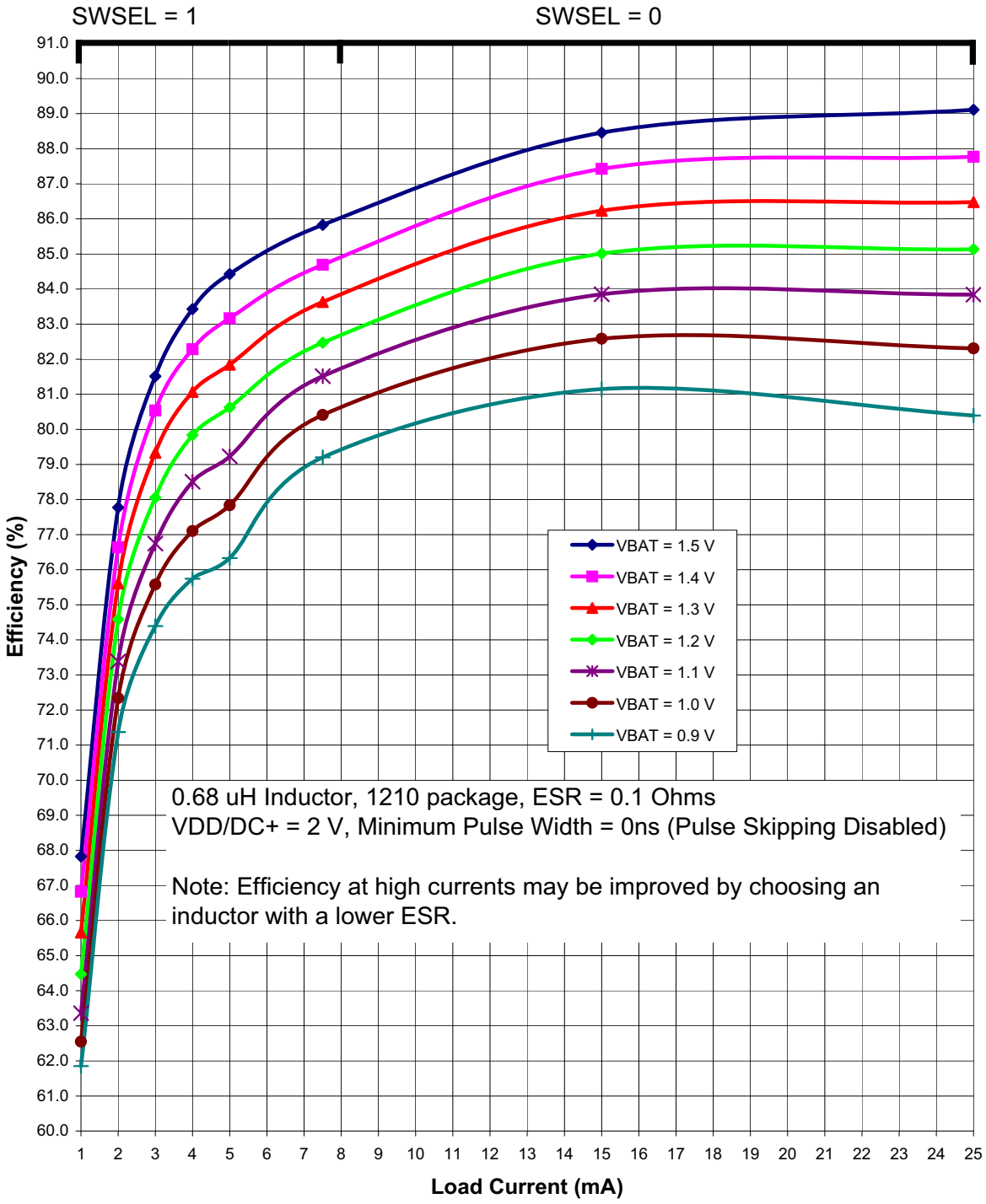


Figure 4.3. Typical DC-DC Converter Efficiency (High Current, VDD/DC+ = 2 V)

Table 4.10. Temperature Sensor Electrical Characteristics

V_{DD} = 1.8 to 3.6V V, –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Linearity		—	±1	—	°C
Slope		—	3.40	—	mV/°C
Slope Error*		—	40	—	µV/°C
Offset	Temp = 25 °C	—	1025	—	mV
Offset Error*	Temp = 25 °C	—	18	—	mV
Temperature Sensor Turn-On Time		—	1.7	—	µs
Supply Current		—	35	—	µA
***Note:** Represents one standard deviation from the mean.					

Table 4.11. Voltage Reference Electrical Characteristics

V_{DD} = 1.8 to 3.6 V, –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Internal High Speed Reference (REFSL[1:0] = 11)					
Output Voltage	–40 to +85 °C, V_{DD} = 1.8–3.6 V	1.60	1.65	1.70	V
VREF Turn-on Time		—	—	1.5	µs
Supply Current		—	200	—	µA
Internal Precision Reference (REFSL[1:0] = 00, REFOE = 1)					
Output Voltage	–40 to +85 °C, V_{DD} = 1.8–3.6 V	1.645	1.680	1.715	V
VREF Short-Circuit Current		—	3.5	—	mA
Load Regulation	Load = 0 to 200 µA to AGND	—	400	—	µV/µA
VREF Turn-on Time 1	4.7 µF tantalum, 0.1 µF ceramic bypass, settling to 0.5 LSB	—	15	—	ms
VREF Turn-on Time 2	0.1 µF ceramic bypass, settling to 0.5 LSB	—	300	—	µs
VREF Turn-on Time 3	no bypass cap, settling to 0.5 LSB	—	25	—	µs
Supply Current		—	15	—	µA
External Reference (REFSL[1:0] = 00, REFOE = 0)					
Input Voltage Range		0	—	V_{DD}	V
Input Current	Sample Rate = 300 ksps; VREF = 3.0 V	—	5.25	—	µA

Table 4.14. DC-DC Converter (DC0) Electrical Characteristics

VBAT = 0.9 to 1.8 V, –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Input Voltage Range		0.9	—	1.8	V
Input Inductor Value		500	680	900	nH
Input Inductor Current Rating		250	—	—	mA
Inductor DC Resistance		—	—	0.5	Ω
Input Capacitor Value	 Source Impedance < 2 Ω	— —	4.7 1.0	— —	µF
Output Voltage Range	Target Output = 1.8 V Target Output = 1.9 V Target Output = 2.0 V Target Output = 2.1 V Target Output = 2.4 V Target Output = 2.7 V Target Output = 3.0 V Target Output = 3.3 V	1.73 1.83 1.93 2.03 2.30 2.60 2.90 3.18	1.80 1.90 2.00 2.10 2.40 2.70 3.00 3.30	1.87 1.97 2.07 2.17 2.50 2.80 3.10 3.42	V
Output Load Regulation	Target Output = 2.0 V, 1 to 30 mA Target Output = 3.0 V, 1 to 20 mA	— —	±0.3 ±1	— —	%
Output Current (based on output power spec)	Target Output = 1.8 V Target Output = 1.9 V Target Output = 2.0 V Target Output = 2.1 V Target Output = 2.4 V Target Output = 2.7 V Target Output = 3.0 V Target Output = 3.3 V	— — — — — — — —	— — — — — — — —	36 34 32 30 27 24 21 19	mA
Output Power		—	—	65	mW
Bias Current	from VBAT supply from VDD/DC+ supply	— —	80 100	— —	µA
Clocking Frequency		1.6	2.4	3.2	MHz
Maximum DC Load Current During Startup		—	—	1	mA
Capacitance Connected to Output		0.8	1.0	2.0	µF

Table 4.15. VREG0 Electrical Characteristics

V_{DD} = 1.8 to 3.6 V, –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Input Voltage Range		1.8	—	3.6	V
Bias Current	Normal, Idle, Suspend, or Stop Mode	—	20	—	µA

5.2.4. Settling Time Requirements

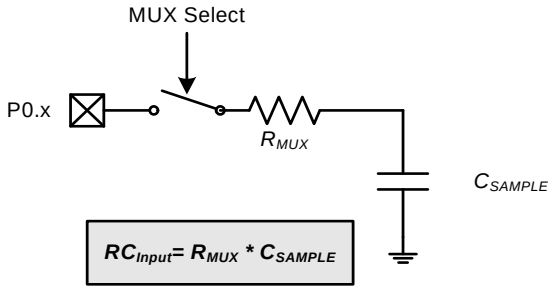
A minimum amount of tracking time is required before each conversion can be performed, to allow the sampling capacitor voltage to settle. This tracking time is determined by the AMUX0 resistance, the ADC0 sampling capacitance, any external source resistance, and the accuracy required for the conversion. Note that in low-power tracking mode, three SAR clocks are used for tracking at the start of every conversion. For many applications, these three SAR clocks will meet the minimum tracking time requirements, and higher values for the external source impedance will increase the required tracking time.

Figure 5.4 shows the equivalent ADC0 input circuit. The required ADC0 settling time for a given settling accuracy (SA) may be approximated by Equation 5.1. When measuring the Temperature Sensor output or V_{DD} with respect to GND, R_{TOTAL} reduces to R_{MUX}. See Table 4.9 for ADC0 minimum settling time requirements as well as the mux impedance and sampling capacitor values.

$$t = \ln\left(\frac{2^n}{SA}\right) \times R_{TOTAL} C_{SAMPLE}$$

Equation 5.1. ADC0 Settling Time Requirements

Where:
SA is the settling accuracy, given as a fraction of an LSB (for example, 0.25 to settle within 1/4 LSB)
t is the required settling time in seconds
R_{TOTAL} is the sum of the AMUX0 resistance and any external source resistance.
n is the ADC resolution in bits (10).



Note: The value of CSAMPLE depends on the PGA Gain. See Table 4.9 for details.

Figure 5.4. ADC0 Equivalent Input Circuits

5.7. Voltage and Ground Reference Options

The voltage reference MUX is configurable to use an externally connected voltage reference, one of two internal voltage references, or one of two power supply voltages (see Figure 5.10). The ground reference MUX allows the ground reference for ADC0 to be selected between the ground pin (GND) or a port pin dedicated to analog ground (P0.1/AGND).

The voltage and ground reference options are configured using the REF0CN SFR described on page 88. Electrical specifications are can be found in the Electrical Specifications Chapter.

Important Note About the V_{REF} and AGND Inputs: Port pins are used as the external V_{REF} and AGND inputs. When using an external voltage reference or the internal precision reference, P0.0/VREF should be configured as an analog input and skipped by the Digital Crossbar. When using AGND as the ground reference to ADC0, P0.1/AGND should be configured as an analog input and skipped by the Digital Crossbar. Refer to Section “21. Port Input/Output” on page 212 for complete Port I/O configuration details. The external reference voltage must be within the range $0 \le V_{REF} \le$ VDD/DC+ and the external ground reference must be at the same DC voltage potential as GND.

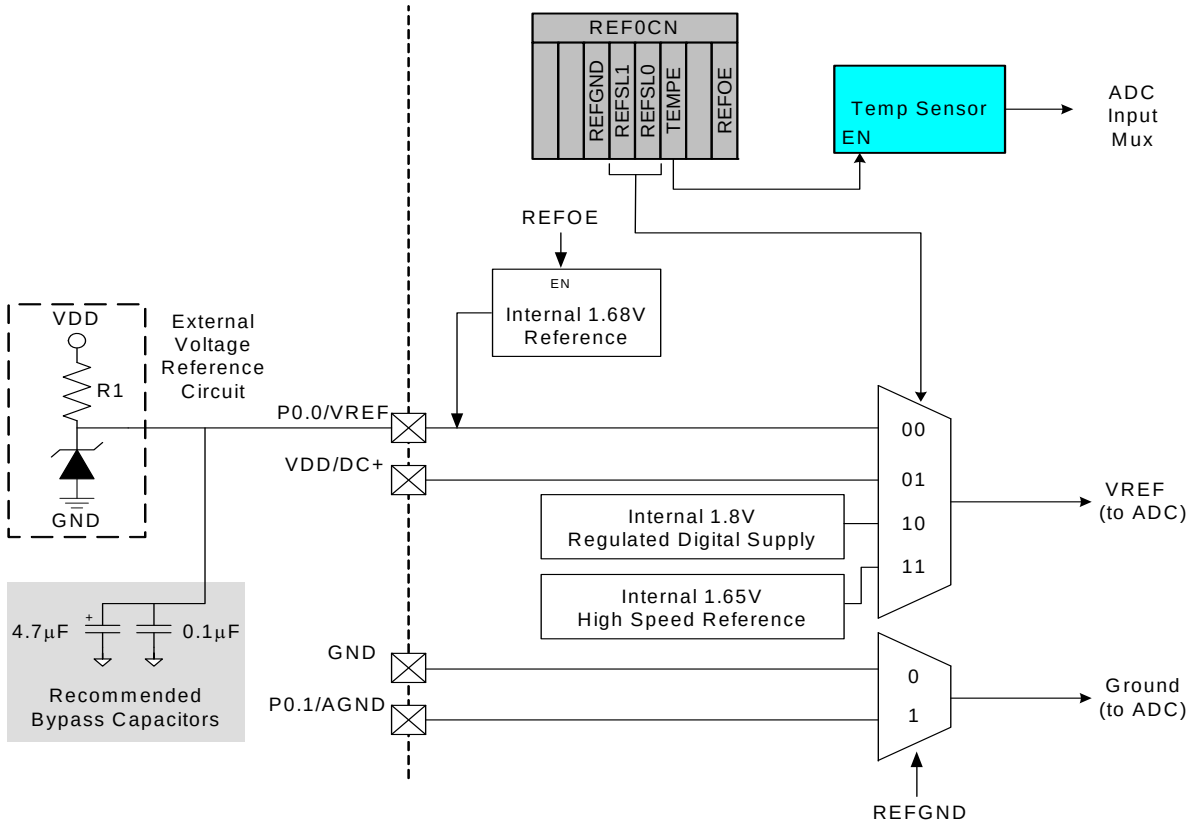


Figure 5.10. Voltage Reference Functional Block Diagram

6. Programmable Current Reference (IREF0)

C8051F93x-C8051F92x devices include an on-chip programmable current reference (source or sink) with two output current settings: Low Power Mode and High Current Mode. The maximum current output in Low Power Mode is 63 µA (1 µA steps) and the maximum current output in High Current Mode is 504 µA (8 µA steps).

The current source/sink is controlled though the IREF0CN special function register. It is enabled by setting the desired output current to a non-zero value. It is disabled by writing 0x00 to IREF0CN. The port I/O pin associated with ISRC0 should be configured as an analog input and skipped in the Crossbar. See Section “21. Port Input/Output” on page 212 for more details.

SFR Definition 6.1. IREF0CN: Current Reference Control

Bit	7	6	5	4	3	2	1	0
Name	SINK	MODE	IREF0DAT					
Type	R/W	R/W	R/W					
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xB9

Bit	Name	Function
7	SINK	**IREF0 Current Sink Enable.** Selects if IREF0 is a current source or a current sink. 0: IREF0 is a current source. 1: IREF0 is a current sink.
6	MDSEL	**IREF0 Output Mode Select.** Selects Low Power or High Current Mode. 0: Low Power Mode is selected (step size = 1 µA). 1: High Current Mode is selected (step size = 8 µA).
5:0	IREF0DAT[5:0]	**IREF0 Data Word.** Specifies the number of steps required to achieve the desired output current. Output current = direction x step size x IREF0DAT. IREF0 is in a low power state when IREF0DAT is set to 0x00.

6.1. IREF0 Specifications

See Table 4.12 on page 61 for a detailed listing of IREF0 specifications.

SFR Definition 7.4. CPT1MD: Comparator 1 Mode Selection

Bit	7	6	5	4	3	2	1	0
Name			CP1RIE	CP1FIE			CP1MD[1:0]	
Type	R/W	R	R/W	R/W	R	R	R/W	
Reset	1	0	0	0	0	0	1	0

SFR Page = 0x0; SFR Address = 0x9C

Bit	Name	Function
7	Reserved	Reserved. Read = 1b, Must Write 1b.
6	Unused	**Unused.** Read = 00b, Write = don't care.
5	CP1RIE	**Comparator1 Rising-Edge Interrupt Enable.** 0: Comparator1 Rising-edge interrupt disabled. 1: Comparator1 Rising-edge interrupt enabled.
4	CP1FIE	**Comparator1 Falling-Edge Interrupt Enable.** 0: Comparator1 Falling-edge interrupt disabled. 1: Comparator1 Falling-edge interrupt enabled.
3:2	Unused	**Unused.** Read = 00b, Write = don't care.
1:0	CP1MD[1:0]	**Comparator1 Mode Select** These bits affect the response time and power consumption for Comparator1. 00: Mode 0 (Fastest Response Time, Highest Power Consumption) 01: Mode 1 10: Mode 2 11: Mode 3 (Slowest Response Time, Lowest Power Consumption)

9.2.1.3. Stack

A programmer's stack can be located anywhere in the 256-byte data memory. The stack area is designated using the Stack Pointer (SP) SFR. The SP will point to the last location used. The next value pushed on the stack is placed at SP+1 and then SP is incremented. A reset initializes the stack pointer to location 0x07. Therefore, the first value pushed on the stack is placed at location 0x08, which is also the first register (R0) of register bank 1. Thus, if more than one register bank is to be used, the SP should be initialized to a location in the data memory not being used for data storage. The stack depth can extend up to 256 bytes.

9.2.2. External RAM

There are 4096 bytes of on-chip RAM mapped into the external data memory space. All of these address locations may be accessed using the external move instruction (MOVX) and the data pointer (DPTR), or using MOVX indirect addressing mode (such as @R1) in combination with the EMI0CN register. Additional off-chip memory or memory-mapped devices may be mapped to the external memory address space and accessed using the external memory interface. See Section “10. External Data Memory Interface and On-Chip XRAM” on page 113 for further details.

SFR Definition 12.6. EIP2: Extended Interrupt Priority 2

Bit	7	6	5	4	3	2	1	0
Name					PSPI1	PRTC0F	PMAT	PWARN
Type	R	R	R	R	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Page = All Pages; SFR Address = 0xF7

Bit	Name	Function
7:4	Unused	**Unused.** Read = 0000b. Write = Don't care.
3	PSPI1	**Serial Peripheral Interface (SPI1) Interrupt Priority Control.** This bit sets the priority of the SPI1 interrupt. 0: SP1 interrupt set to low priority level. 1: SPI1 interrupt set to high priority level.
2	PRTC0F	**SmaRTClock Oscillator Fail Interrupt Priority Control.** This bit sets the priority of the SmaRTClock Alarm interrupt. 0: SmaRTClock Alarm interrupt set to low priority level. 1: SmaRTClock Alarm interrupt set to high priority level.
1	PMAT	**Port Match Interrupt Priority Control.** This bit sets the priority of the Port Match Event interrupt. 0: Port Match interrupt set to low priority level. 1: Port Match interrupt set to high priority level.
0	PWARN	**VDD/DC+ Supply Monitor Early Warning Interrupt Priority Control.** This bit sets the priority of the VDD/DC+ Supply Monitor Early Warning interrupt. 0: VDD/DC+ Supply Monitor Early Warning interrupt set to low priority level. 1: VDD/DC+ Supply Monitor Early Warning interrupt set to high priority level.

13.4. Determining the Device Part Number at Run Time

In many applications, user software may need to determine the MCU part number at run time in order to determine the hardware capabilities. The part number can be determined by reading the value of the Flash byte at address 0xFFFE.

The value of the Flash byte at address 0xFFFE can be decoded as follows:

0x56—C8051F930
0x5E—C8051F931
0xB1—C8051F920
0xB3—C8051F921

17. Voltage Regulator (VREG0)

C8051F93x-C8051F92x devices include an internal voltage regulator (VREG0) to regulate the internal core supply to 1.8 V from a VDD/DC+ supply of 1.8 to 3.6 V. Electrical characteristics for the on-chip regulator are specified in the Electrical Specifications chapter.

The REG0CN register allows the Precision Oscillator Bias to be disabled, reducing supply current in all non-sleep power modes. This bias should only be disabled when the precision oscillator is not being used.

The internal regulator (VREG0) is disabled when the device enters sleep mode and remains enabled when the device enters suspend mode. See Section “14. Power Management” on page 156 for complete details about low power modes.

SFR Definition 17.1. REG0CN: Voltage Regulator Control

Bit	7	6	5	4	3	2	1	0
Name		Reserved	Reserved	OSCBIAS				Reserved
Type	R	R/W	R/W	R/W	R	R	R	R/W
Reset	0	0	0	1	0	0	0	0

SFR Page = 0x0; SFR Address = 0xC9

Bit	Name	Function
7	Unused	**Unused.** Read = 0b. Write = Don’t care.
6	Reserved	**Reserved.** Read = 0b. Must Write 0b.
5	Reserved	**Reserved.** Read = 0b. Must Write 0b.
4	OSCBIAS	**Precision Oscillator Bias.** When set to 1, the bias used by the precision oscillator is forced on. If the precision oscillator is not being used, this bit may be cleared to 0 to save approximately 80 µA of supply current in all non-Sleep power modes. If disabled then re-enabled, the precision oscillator bias requires 4 µs of settling time.
3:1	Unused	**Unused.** Read = 000b. Write = Don’t care.
0	Reserved	**Reserved.** Read = 0b. Must Write 0b.

17.1. Voltage Regulator Electrical Specifications

See Table 4.15 on page 64 for detailed Voltage Regulator Electrical Specifications.

18.2. Power-Fail (VDD/DC+ Supply Monitor) Reset

C8051F93x-C8051F92x devices have a VDD/DC+ Supply Monitor that is enabled and selected as a reset source after each power-on or power-fail reset. When enabled and selected as a reset source, any power down transition or power irregularity that causes VDD/DC+ to drop below V_{RST} will cause the $\overline{RST}$ pin to be driven low and the CIP-51 will be held in a reset state (see Figure 18.3). When VDD/DC+ returns to a level above V_{RST}, the CIP-51 will be released from the reset state.

After a power-fail reset, the PORSF flag reads 1, the contents of RAM invalid, and the VDD/DC+ supply monitor is enabled and selected as a reset source. The enable state of the VDD/DC+ supply monitor and its selection as a reset source is only altered by power-on and power-fail resets. For example, if the VDD/DC+ supply monitor is de-selected as a reset source and disabled by software, then a software reset is performed, the VDD/DC+ supply monitor will remain disabled and de-selected after the reset.

In battery-operated systems, the contents of RAM can be preserved near the end of the battery's usable life if the device is placed in sleep mode prior to a power-fail reset occurring. When the device is in sleep mode, the power-fail reset is automatically disabled and the contents of RAM are preserved as long as the VBAT supply does not fall below V_{POR}. A large capacitor can be used to hold the power supply voltage above V_{POR} while the user is replacing the battery. Upon waking from sleep mode, the enable and reset source select state of the VDD/DC+ supply monitor are restored to the value last set by the user.

To allow software early notification that a power failure is about to occur, the VDDOK bit is cleared when the VDD/DC+ supply falls below the V_{WARN} threshold. The VDDOK bit can be configured to generate an interrupt. See Section "12. Interrupt Handler" on page 133 for more details.

Important Note: To protect the integrity of Flash contents, **the VDD/DC+ supply monitor must be enabled and selected as a reset source if software contains routines which erase or write Flash memory.** If the VDD/DC+ supply monitor is not enabled, any erase or write performed on Flash memory will cause a Flash Error device reset.

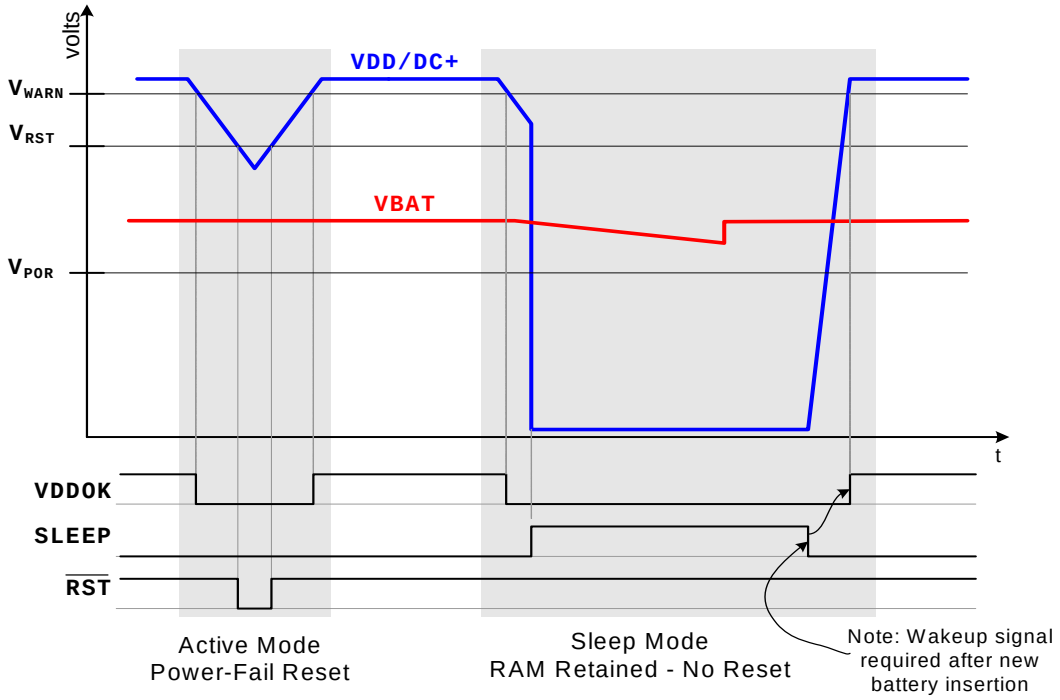


Figure 18.3. Power-Fail Reset Timing Diagram

20.2.4. Automatic Gain Control (Crystal Mode Only) and SmaRTClock Bias Doubling

Automatic Gain Control allows the SmaRTClock oscillator to trim the oscillation amplitude of a crystal in order to achieve the lowest possible power consumption. Automatic Gain Control automatically detects when the oscillation amplitude has reached a point where it safe to reduce the drive current, therefore, it may be enabled during crystal startup. It is recommended to enable Automatic Gain Control in most systems which use the SmaRTClock oscillator in Crystal Mode. The following are recommended crystal specifications and operating conditions when Automatic Gain Control is enabled:

- ESR < 50 kΩ
- Load Capacitance < 10 pF
- Supply Voltage < 3.0 V
- Temperature > –20 °C

When using Automatic Gain Control, it is recommended to perform an oscillation robustness test to ensure that the chosen crystal will oscillate under the worst case condition to which the system will be exposed. The worst case condition that should result in the least robust oscillation is at the following system conditions: lowest temperature, highest supply voltage, highest ESR, highest load capacitance, and lowest bias current (AGC enabled, Bias Double Disabled).

To perform the oscillation robustness test, the SmaRTClock oscillator should be enabled and selected as the system clock source. Next, the SYSCLK signal should be routed to a port pin configured as a push-pull digital output. The positive duty cycle of the output clock can be used as an indicator of oscillation robustness. As shown in Figure 20.2, duty cycles less than 55% indicate a robust oscillation. As the duty cycle approaches 60%, oscillation becomes less reliable and the risk of clock failure increases. Increasing the bias current (by disabling AGC) will always improve oscillation robustness and will reduce the output clock's duty cycle. This test should be performed at the worst case system conditions, as results at very low temperatures or high supply voltage will vary from results taken at room temperature or low supply voltage.

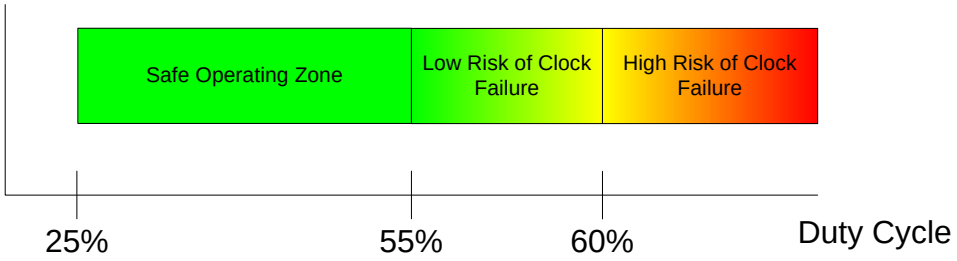


Figure 20.2. Interpreting Oscillation Robustness (Duty Cycle) Test Results

As an alternative to performing the oscillation robustness test, Automatic Gain Control may be disabled at the cost of increased power consumption (approximately 200 nA). Disabling Automatic Gain Control will provide the crystal oscillator with higher immunity against external factors which may lead to clock failure. Automatic Gain Control must be disabled if using the SmaRTClock oscillator in self-oscillate mode.

22.4.2. SMB0CN Control Register

SMB0CN is used to control the interface and to provide status information (see SFR Definition 22.2). The higher four bits of SMB0CN (MASTER, TXMODE, STA, and STO) form a status vector that can be used to jump to service routines. MASTER indicates whether a device is the master or slave during the current transfer. TXMODE indicates whether the device is transmitting or receiving data for the current byte.

STA and STO indicate that a START and/or STOP has been detected or generated since the last SMBus interrupt. STA and STO are also used to generate START and STOP conditions when operating as a master. Writing a 1 to STA will cause the SMBus interface to enter Master Mode and generate a START when the bus becomes free (STA is not cleared by hardware after the START is generated). Writing a 1 to STO while in Master Mode will cause the interface to generate a STOP and end the current transfer after the next ACK cycle. If STO and STA are both set (while in Master Mode), a STOP followed by a START will be generated.

The ARBLOST bit indicates that the interface has lost an arbitration. This may occur anytime the interface is transmitting (master or slave). A lost arbitration while operating as a slave indicates a bus error condition. ARBLOST is cleared by hardware each time SI is cleared.

The SI bit (SMBus Interrupt Flag) is set at the beginning and end of each transfer, after each byte frame, or when an arbitration is lost; see Table 22.3 for more details.
Important Note About the SI Bit: The SMBus interface is stalled while SI is set; thus SCL is held low, and the bus is stalled until software clears SI.

22.4.2.1.Software ACK Generation

When the EHACK bit in register SMB0ADM is cleared to 0, the firmware on the device must detect incoming slave addresses and ACK or NACK the slave address and incoming data bytes. As a receiver, writing the ACK bit defines the outgoing ACK value; as a transmitter, reading the ACK bit indicates the value received during the last ACK cycle. ACKRQ is set each time a byte is received, indicating that an outgoing ACK value is needed. When ACKRQ is set, software should write the desired outgoing value to the ACK bit before clearing SI. A NACK will be generated if software does not write the ACK bit before clearing SI. SDA will reflect the defined ACK value immediately following a write to the ACK bit; however SCL will remain low until SI is cleared. If a received slave address is not acknowledged, further slave events will be ignored until the next START is detected.

22.4.2.2.Hardware ACK Generation

When the EHACK bit in register SMB0ADM is set to 1, automatic slave address recognition and ACK generation is enabled. More detail about automatic slave address recognition can be found in Section 22.4.3. As a receiver, the value currently specified by the ACK bit will be automatically sent on the bus during the ACK cycle of an incoming data byte. As a transmitter, reading the ACK bit indicates the value received on the last ACK cycle. The ACKRQ bit is not used when hardware ACK generation is enabled. If a received slave address is NACKed by hardware, further slave events will be ignored until the next START is detected, and no interrupt will be generated.

Table 22.3 lists all sources for hardware changes to the SMB0CN bits. Refer to Table 22.5 for SMBus status decoding using the SMB0CN register.

Refer to the C8051F930 errata when using hardware ACK generation on C8051F930/31/20/21 devices.

23.2.2. 9-Bit UART

9-bit UART mode uses a total of eleven bits per data byte: a start bit, 8 data bits (LSB first), a programmable ninth data bit, and a stop bit. The state of the ninth transmit data bit is determined by the value in TB80 (SCON0.3), which is assigned by user software. It can be assigned the value of the parity flag (bit P in register PSW) for error detection, or used in multiprocessor communications. On receive, the ninth data bit goes into RB80 (SCON0.2) and the stop bit is ignored.

Data transmission begins when an instruction writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to 1. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: (1) RI0 must be logic 0, and (2) if MCE0 is logic 1, the 9th bit must be logic 1 (when MCE0 is logic 0, the state of the ninth data bit is unimportant). If these conditions are met, the eight bits of data are stored in SBUF0, the ninth bit is stored in RB80, and the RI0 flag is set to 1. If the above conditions are not met, SBUF0 and RB80 will not be loaded and the RI0 flag will not be set to 1. A UART0 interrupt will occur if enabled when either TI0 or RI0 is set to 1.

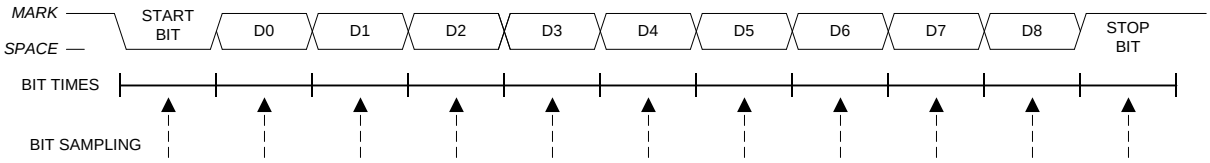


Figure 23.5. 9-Bit UART Timing Diagram

23.3. Multiprocessor Communications

9-Bit UART mode supports multiprocessor communication between a master processor and one or more slave processors by special use of the ninth data bit. When a master processor wants to transmit to one or more slaves, it first sends an address byte to select the target(s). An address byte differs from a data byte in that its ninth bit is logic 1; in a data byte, the ninth bit is always set to logic 0.

Setting the MCE0 bit (SCON0.5) of a slave processor configures its UART such that when a stop bit is received, the UART will generate an interrupt only if the ninth bit is logic 1 (RB80 = 1) signifying an address byte has been received. In the UART interrupt handler, software will compare the received address with the slave's own assigned 8-bit address. If the addresses match, the slave will clear its MCE0 bit to enable interrupts on the reception of the following data byte(s). Slaves that weren't addressed leave their MCE0 bits set and do not generate interrupts on the reception of the following data bytes, thereby ignoring the data. Once the entire message is received, the addressed slave resets its MCE0 bit to ignore all transmissions until it receives the next address byte.

Multiple addresses can be assigned to a single slave and/or a single address can be assigned to multiple slaves, thereby enabling "broadcast" transmissions to more than one slave simultaneously. The master processor can be configured to receive all transmissions or a protocol can be implemented such that the master/slave role is temporarily reversed to enable half-duplex transmission between the original master and slave(s).

25.2.2. 8-bit Timers with Auto-Reload

When T2SPLIT is set, Timer 2 operates as two 8-bit timers (TMR2H and TMR2L). Both 8-bit timers operate in auto-reload mode as shown in Figure 25.5. TMR2RLL holds the reload value for TMR2L; TMR2RLH holds the reload value for TMR2H. The TR2 bit in TMR2CN handles the run control for TMR2H. TMR2L is always running when configured for 8-bit Mode.

Each 8-bit timer may be configured to use SYSCLK, SYSCLK divided by 12, SmaRTClock divided by 8 or Comparator 0 output. The Timer 2 Clock Select bits (T2MH and T2ML in CKCON) select either SYSCLK or the clock defined by the Timer 2 External Clock Select bits (T2XCLK[1:0] in TMR2CN), as follows:

T2MH	T2XCLK[1:0]	TMR2H Clock Source
0	00	SYSCLK / 12
0	01	SmaRTClock / 8
0	10	Reserved
0	11	Comparator 0
1	X	SYSCLK

T2ML	T2XCLK[1:0]	TMR2L Clock Source
0	00	SYSCLK / 12
0	01	SmaRTClock / 8
0	10	Reserved
0	11	Comparator 0
1	X	SYSCLK

The TF2H bit is set when TMR2H overflows from 0xFF to 0x00; the TF2L bit is set when TMR2L overflows from 0xFF to 0x00. When Timer 2 interrupts are enabled (IE.5), an interrupt is generated each time TMR2H overflows. If Timer 2 interrupts are enabled and TF2LEN (TMR2CN.5) is set, an interrupt is generated each time either TMR2L or TMR2H overflows. When TF2LEN is enabled, software must check the TF2H and TF2L flags to determine the source of the Timer 2 interrupt. The TF2H and TF2L interrupt flags are not cleared by hardware and must be manually cleared by software.

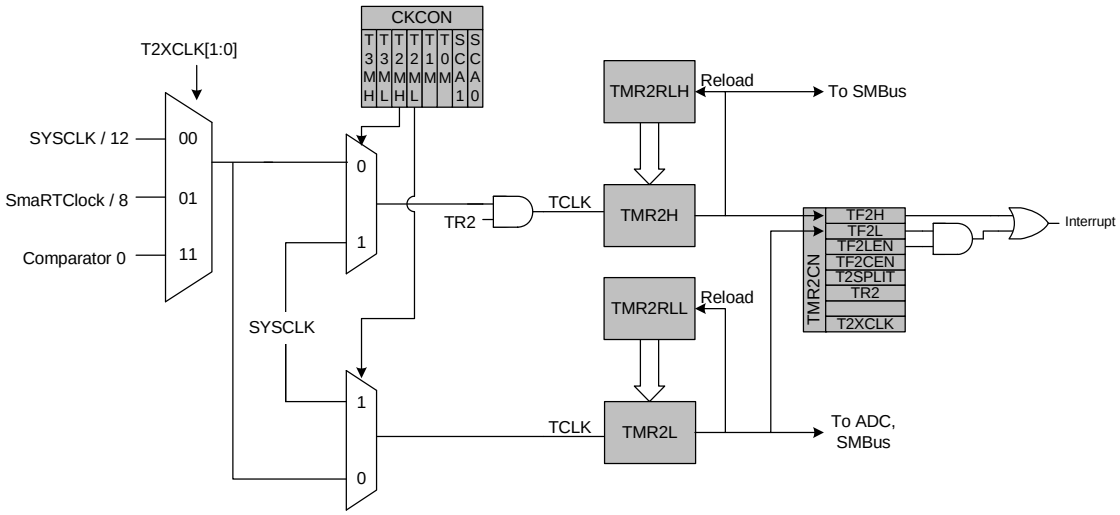


Figure 25.5. Timer 2 8-Bit Mode Block Diagram

25.2.3. Comparator 0/SmaRTClock Capture Mode

The Capture Mode in Timer 2 allows either Comparator 0 or the SmaRTClock period to be measured against the system clock or the system clock divided by 12. Comparator 0 and the SmaRTClock period can also be compared against each other. Timer 2 Capture Mode is enabled by setting TF2CEN to 1. Timer 2 should be in 16-bit auto-reload mode when using Capture Mode.

When Capture Mode is enabled, a capture event will be generated either every Comparator 0 rising edge or every 8 SmaRTClock clock cycles, depending on the T2XCLK1 setting. When the capture event occurs, the contents of Timer 2 (TMR2H:TMR2L) are loaded into the Timer 2 reload registers (TMR2RLH:TMR2RLL) and the TF2H flag is set (triggering an interrupt if Timer 2 interrupts are enabled). By recording the difference between two successive timer capture values, the Comparator 0 or SmaRTClock period can be determined with respect to the Timer 2 clock. The Timer 2 clock should be much faster than the capture clock to achieve an accurate reading.

For example, if T2ML = 1b, T2XCLK1 = 0b, and TF2CEN = 1b, Timer 2 will clock every SYSCLK and capture every SmaRTClock clock divided by 8. If the SYSCLK is 24.5 MHz and the difference between two successive captures is 5984, then the SmaRTClock clock is:

24.5 MHz/(5984/8) = 0.032754 MHz or 32.754 kHz.

This mode allows software to determine the exact SmaRTClock frequency in self-oscillate mode and the time between consecutive Comparator 0 rising edges, which is useful for detecting changes in the capacitance of a Touch Sense Switch.

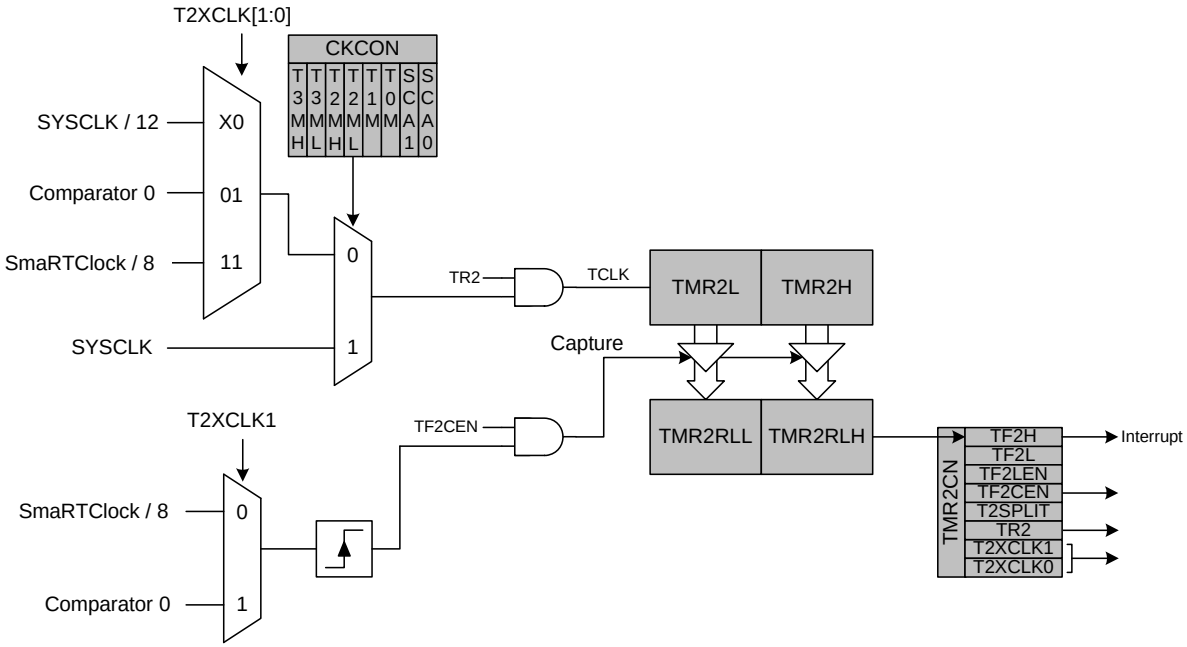


Figure 25.6. Timer 2 Capture Mode Block Diagram

SFR Definition 25.14. TMR3RLL: Timer 3 Reload Register Low Byte

Bit	7	6	5	4	3	2	1	0
Name	TMR3RLL[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0x92

Bit	Name	Function
7:0	TMR3RLL[7:0]	**Timer 3 Reload Register Low Byte.** TMR3RLL holds the low byte of the reload value for Timer 3.

SFR Definition 25.15. TMR3RLH: Timer 3 Reload Register High Byte

Bit	7	6	5	4	3	2	1	0
Name	TMR3RLH[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0x93

Bit	Name	Function
7:0	TMR3RLH[7:0]	**Timer 3 Reload Register High Byte.** TMR3RLH holds the high byte of the reload value for Timer 3.

C2 Register Definition 27.4. FPCTL: C2 Flash Programming Control

Bit	7	6	5	4	3	2	1	0
Name	FPCTL[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

C2 Address: 0x02

Bit	Name	Function
7:0	FPCTL[7:0]	**Flash Programming Control Register.** This register is used to enable Flash programming via the C2 interface. To enable C2 Flash programming, the following codes must be written in order: 0x02, 0x01. Note that once C2 Flash programming is enabled, a system reset must be issued to resume normal operation.

C2 Register Definition 27.5. FPDAT: C2 Flash Programming Data

Bit	7	6	5	4	3	2	1	0
Name	FPDAT[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

C2 Address: 0xB4

Bit	Name	Function	
7:0	FPDAT[7:0]	**C2 Flash Programming Data Register.** This register is used to pass Flash commands, addresses, and data during C2 Flash accesses. Valid commands are listed below.	
		Code	**Command**
		0x06	Flash Block Read
		0x07	Flash Block Write
		0x08	Flash Page Erase
		0x03	Device Erase